Yuling Niu

List of Publications by Year
in descending order

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21	247	1307594 7	1588992 8
papers	citations	h-index	g-index

21	21	21	96
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Comprehensive Study on 2.5D Package Design for Board-Level Reliability in Thermal Cycling and Power Cycling. , 2018, , .		31
2	Design Guideline of 2.5D Package with Emphasis on Warpage Control and Thermal Management. , 2018, , .		29
3	A comprehensive solution for electronic packages' reliability assessment with digital image correlation (DIC) method. Microelectronics Reliability, 2018, 87, 81-88.	1.7	21
4	A comprehensive solution for modeling moisture induced delamination in electronic packaging during solder reflow. Microelectronics Reliability, 2020, 112, 113791.	1.7	18
5	Modeling and Design of 2.5D Package with Mitigated Warpage and Enhanced Thermo-Mechanical Reliability. , 2018, , .		17
6	In-Situ Warpage Characterization of BGA Packages with Solder Balls Attached During Reflow with 3D Digital Image Correlation (DIC). , 2016, , .		14
7	The Expermental and Numerical Study of Electromigration in 2.5D Packaging. , 2018, , .		14
8	A general strategy of in-situ warpage characterization for solder attached packages with digital image correlation method. Optics and Lasers in Engineering, 2017, 93, 9-18.	3.8	13
9	A Novel Speckle-Free Digital Image Correlation Method for In Situ Warpage Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, , 1-9.	2.5	13
10	A new in-situ warpage measurement of a wafer with speckle -free digital image correlation (DIC) method. , 2015, , .		11
11	The Complete Packaging Reliability Studies through One Digital Image Correlation System. , 2017, , .		10
12	An Accurate Experimental Determination of Effective Strain for Heterogeneous Electronic Packages With Digital Image Correlation Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 678-688.	2.5	10
13	An Investigation of Moisture-Induced Interfacial Delamination in Plastic IC Package During Solder Reflow. , 2017, , .		8
14	A Study on the Thermomechanical Reliability Risks of Through-Silicon-Vias in Sensor Applications. Sensors, 2017, 17, 322.	3.8	8
15	Experimentally Minimizing the Gap Distance Between Extra Tall Packages and PCB Using the Digital Image Correlation (DIC) Method. , 2018, , .		8
16	Design guideline on board-level thermomechanical reliability of 2.5D package. Microelectronics Reliability, 2020, 111, 113701.	1.7	8
17	Die stress in stealth dicing for MEMS. , 2016, , .		6
18	Warpage Variation Analysis and Model Prediction for Molded Packages. , 2019, , .		3

#	Article	IF	Citations
19	An Experimental and Numerical Study of the Dynamic Fracture of Glass. , 2013, , .		2
20	Mechanical Strength Characterization of Direct Bond Interfaces for 3D-IC and MEMS Applications. , 2018, , .		2
21	Accessible determination of die-to-wafer bond strength with the Schwickerath test. Engineering Fracture Mechanics, 2020, 229, 106929.	4.3	1